



### S3A1U3-B1B-i1

#### 1U Backplane with Single Gen 3.0 Express Module I/O for Intel S1600JP

##### Product Description

The Silicom SETAC is a solution that converts a standard server to a network appliance.



- Front system I/O ports
- I/O modules can be replaced without opening the server chassis
- Higher ports density than a standard server
- More reliable solution than a standard PCI Express NIC

SETAC Network appliances are based on standard server with front hot-swap HD. The SETAC Network appliance includes SETAC backplane that replaces a server HD backplane. In a standard server, a HD backplane supports only SAS / SATA technology – Silicom SETAC backplane supports PCI Express and SAS / SATA technology.

Silicom SETAC solution based on Silicom ExpressModule cards, providing widest networking and Bypass solution. The Silicom' s S3A2U3-A2 is Express x16 Gen 3.0 Host Connector to Two TWINAX Connectors Interface Adapter.

##### Key Features

- Based on server grade reliability
- Leverage the price / performance / reliability of standard server
- Maximize the I/O ports and interfaces
- Field replaceable – End user can change the configuration without opening of sever chassis
- High quantity of various configurations can be efficiently handled and final configuration can be done just before shipment
- Server and IO module flexibility:
- Based on standard server
- Based on Silicom ExpressModule cards
- Simpler maintenance – Components can be replaced quickly and assuredly

##### Reliable solution:

- Based on current SATA backplane
- Better than SATA cables

- Better than standard add-in PCI form factor
- Redundant PSU (1+1), low cost model with single PSU
- Standard dimension motherboard (12x13) with next generation NEHALEM CPUs
- Based on embedded solutions –Up to 5 years product life cycle

**Host Interface:**

- Host Interface standard support PCI Express 3.0 (8Gb/s)
- PCI Express X8 lanes
- Signaling and interface based on PCI-Express EM standard (PCI-SIG) ver. 3.0 (8.0 GT/s)
- Module Width same as standard of 3.5" Hard Disk (101.6mm)
- Module install to 3.5" Hard disk Bay of rack mountable server
- PCI-E EM Backplane replacing HD Backplane
- PCI Express ExpressModule Electromechanical Specification Revision 1.0 (2.0)
- PCI Express External Cabling Specification Revision 1.0 (2.0)
- PCI Express External Cabling Specification 2.0 Revision 0.3 RC2
- PCI Express External Cabling Specification 3.0 Revision 1.0

**Technical Specifications**

General Technical Specifications	
<b>Size:</b>	3.858" x 1.063" (97.99 mm x 27 mm)
<b>Voltage:</b>	+12V (Min 11.04V, Max, 12.96V)
<b>Weight:</b>	20 gr (0.706 oz )
<b>Power Consumption:</b>	0.48W, 0.04A at 12V: Typical without SETAC module 3.24W, 0.27A at 12V: Typical with SETAC module
<b>Ports</b>	Up to 8 NIC (SFP/Copper)
<b>Modules</b>	Up to 1 SETAC Module
<b>Operating Humidity:</b>	0%–90%, non-condensing
<b>Operating Temperature:</b>	0°C – 50°C (32°F – 122°F)
<b>Storage Temperature:</b>	-20°C–65°C (-4°F–149°F)

<b>EMC Certifications:</b>	Class B
<b>MTBF*:</b>	821(Years) *According to Telcordia SR-332 Issue 2 Environmental condition – GB (Ground, Fixed, Controlled). Ambient temperature – 40°C
<b>Connector Specifications</b>	
<b>Connectors:</b>	(1) PCI-E Connector (1) iPass Connector (1) 0.100" (2.54mm) SL™ Header

### Order Information

P/N	Description	Notes
<b>S3A1U3-B1B-i1</b>	1U Backplane with Single Gen 3.0 Express Module I/O, Intel S1600JP	Design for Intel S1600JP

\* Power cable must be connected to backplane S3A1U3-B1B-I1.

\* Backplane S3A1U3-B1B-I1 works only with S3A1U5-A2 Adapter

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